

PRODUCT/PROCESS CHANGE NOTIFICATION (Final)
产品/过程变动通知 (最终)

CGS-060 - 02C

Part 1. PCN Information PCN信息

- 1.1 PCN Number PCN编号: PCN-10-073
- 1.2 Finished date of PCN PCN完成日期: 2011-8-1
- 1.3 PCN Initiator PCN起草人: Pinky Zhang *[Signature]*
- 1.4 PCN Title PCN题目: Cu Wire qualification in SOD123/323/523 packages
- 1.5 Technical Contact 技术上的联系: h.q.wang@takcheong.com / pinky.zhang@takcheong.com
- 1.6 Expected Production Date 预测生产日期: WW36'2011
- 1.7 Package(s) Affected 影响封装: SOD123 / SOD323 / SOD523
- 1.8 List of Affected Devices 影响产品清单: Tak Cheong active SOD123/323/523 Schottky/Zener/Switching devices
- 1.9 Reason(s) of change 变动理由: Copper wire bonding is a modernise process used by different semiconductor suppliers. The main advantage is copper wire has better electrical conductivity. Changing to Cu wire replace current Au wire to remedy the increasing cost of Au material.
- 1.10 Responsible Customer Site / Sale 客户代表/销售代表: *[Signature]*

Part 2. Recommendation 建议

2.1 Process change implementation 执行过程变动

Recommendation 建议

Approved change 批准变动 Disapproved change 不同意变动

Conclusion 结论: The products with Cu wire bonding passed extensive quality test demonstrated the Cu products are assembled with high quality & reliability, therefore, the Cu wire material is approved to be relased for production in TAK SOD123/323/523 packages.

2.2 PCN Board Reviewers PCN评审组

Print Name 打印姓名	Function/Title 功能/职位	Signature 签名	Date 日期	Decision 意见
王小林(代)	制造品控工程师	<i>[Signature]</i>	2011.8-1	OK
王小林	直接上司/部门/高级经理	<i>[Signature]</i>		
赵干祥	QA经理	<i>[Signature]</i>	2011.8.2	OK

2.3 Customer Reviewer (if applicable) 客户评审 (如需要)

() Approval 批准 () Disapproval 不批准

Name 姓名 Title / Function 职位 Date 日期

